
**Te Hiku Hauora Bonding Scholarship
For GPs and Dentists**

Terms and Conditions

Purpose

The purpose of Te Hiku Hauora's Bonding Scholarship programme ("the Scholarship") is to support medical students with the costs associated in obtaining their qualifications, and to support Te Hiku Hauora's recruitment goals.

The scholarships are offered to 4th, 5th and 6th year students enrolled in a Bachelor of Medicine and Bachelor of Surgery degree; or 3rd, 4th and 5th year students enrolled in a Bachelor of Dental Surgery degree.

Each Scholarship is worth \$10,000 per year for a maximum three years or \$30,000.

Expectations

In being offered the Scholarship, the recipient student ("Recipient") is expected to continue with their studies and obtain their Bachelor of Medicine and Bachelor of Surgery or Bachelor of Dental Surgery within the standard timeframe for the course. The Recipient is also expected to maintain satisfactory examination results throughout their studies, and this is necessary before funding for subsequent years is committed to.

In consideration of the Scholarship Funds, upon graduating from their studies and obtaining their qualifications **the Recipient is required to undertake employment with Te Hiku Hauora as a GP, or dentist (or a related medical role) on a full-time basis quid pro quo for every year the scholarship is received ("the Minimum Employment Period") within 10 years after graduation ("the Bonded Period")**. For example, receiving the scholarship for three years requires three years full-time employment, two years requires two years full-time employment, and one year requires one year full-time employment

Where the Recipient undertakes employment with Te Hiku Hauora in accordance with the Scholarship, and the Recipient requests an extended period of leave, including parental/maternity leave but excluding any 'Keeping in Touch' days, which extends beyond 3 consecutive months, any period beyond 3 months will not count towards the "Minimum Employment Period", unless Te Hiku Hauora expressly agrees otherwise.

The offer of employment with Te Hiku Hauora pursuant to the Scholarship is conditional upon the Recipient achieving satisfactory academic performance and Te Hiku Hauora having sufficient resources/funding and capacity to employ the Recipient as a GP, or dentist (or a related medical role).

If Te Hiku Hauora is unable to provide the Recipient employment as a GP, or dentist (or a related medical role) within the “Bonded Period” for part or all of the “Minimum Employment Period”, the Recipient will be advised of this as soon as practicable. In this event, any obligations under the Scholarship will cease, and neither party will have any ongoing obligations to the other. Te Hiku Hauora will not require repayment of the Scholarship Funds in such circumstances.

Repayment

Repayment of the Scholarship Funds will be required in the following circumstances.

Where the Recipient does not achieve satisfactory examination results/fails to obtain their qualification

Where the Recipient identifies that they have not achieved satisfactory examination results and/or that they will be unable to obtain their Bachelor of Medicine and Bachelor of Surgery or Bachelor of Dental Surgery or for any reason, the Recipient must advise Te Hiku Hauora of this as soon as possible.

If the Recipient does not achieve satisfactory examination results, Te Hiku Hauora reserves the right to refuse to pay any further Scholarship Funds for subsequent years of study.

Additionally, if the Recipient fails to obtain their Bachelor of Medicine and Bachelor of Surgery or Bachelor of Dental Surgery due to unsatisfactory examination results or for any other reason, the Recipient will be required to repay all Scholarship Funds they received.

Where the Recipient postpones their studies before obtaining their qualification

Where the Recipient intends to postpone/delay the completion of their studies or their graduation, the Recipient must advise Te Hiku Hauora of this, and the reasons for this postponement/delay, as soon as possible.

Where the Recipient postpones or delays their studies or their graduation, and Te Hiku Hauora does not agree to this postponement/delay, Te Hiku Hauora may require that the Recipient repay all Scholarship Funds they received.

Where the Recipient fails to undertake employment with Te Hiku Hauora for the Minimum Employment Period during the Bonded Period

Where the Recipient identifies that they are/will be unable to undertake employment as a GP or dentist (or a related medical role) with Te Hiku Hauora for part or all of the Minimum Employment Period within the Bonded Period, the Recipient must advise Te Hiku Hauora of this as soon as possible.

Should the Recipient fail to undertake employment with Te Hiku Hauora as a GP or dentist (or a related medical role) for part or all of the “Minimum Employment Period” during the “Bonded Period”, including where the Recipient resigns or is terminated for any reason other than by way of redundancy from their employment with Te Hiku Hauora, the Recipient will be required to repay the Scholarship Funds to Te Hiku Hauora.

General terms for repayment

Where repayment of the Scholarship funds is required, repayment will be pro-rated to reflect the remaining balance under the “Minimum Employment Period” during the “Bonded Period”. For example, where the “Minimum Employment Period” under the Scholarship is three years during the “Bonded Period”, and the Recipient only works for Te Hiku Hauora for one year during the “Bonded Period”, the Recipient would be required to repay 2/3rds of the Scholarship Funds they received.

Where applicable, the Recipient agrees that any repayment of the Scholarship Funds may occur by way of deduction from the Recipient’s final pay with Te Hiku Hauora, and where the Recipient’s final pay is not sufficient to cover the repayment, any balance owing remains as a debt owed to Te Hiku Hauora.

Repayment of the Scholarship Funds must be made in full within 6 months of the Recipient becoming aware of any of the above circumstances which prevent them from performing their obligations under the Scholarship (“the Repayment Period”). Where the Recipient is unable to repay the Scholarship Funds within the “Repayment Period”, the Recipient must advise Te Hiku Hauora of this as soon as possible, and the parties may agree upon terms for a repayment plan. Notwithstanding this, Te Hiku Hauora reserves in rights in respect of any outstanding Scholarship Funds that are to be repaid by the Recipient regardless of any repayment plan being agreed upon by the parties.

In the event that the Scholarship Funds are not repaid within the Repayment Period, Te Hiku Hauora reserves the right to require payment of interest on the balance of the Scholarship Funds to be repaid, at a rate of [5%] per annum [OR] to be calculated in accordance with the Interest on Money Claims Act 2016.

For any questions regarding the Scholarship or queries regarding repayment, please contact Jill Edwards on (09) 4084024 extension 403, or alternatively by email jille@hauora.net.nz

Declaration

1. The Recipient acknowledges that Te Hiku Hauora incurs a cost in providing the Scholarship.
2. In consideration of the expense to Te Hiku Hauora in providing the Scholarship, and in recognition of Te Hiku Hauora’s ongoing recruitment goals, the Recipient agrees to work for Te Hiku Hauora for the Minimum Employment Period within the Bonded Period, subject to Te Hiku Hauora having the capacity and resourcing to offer the Recipient such employment.
3. The Recipient agrees that they have read and understood these Terms and Conditions, and they agree to abide by these Terms and Conditions, including those terms relating to repayment of the Scholarship Funds.

Signed by **[Recipient name]**

Date

Signed by **[insert name]**

on behalf of Te Hiku Hauora

Date
